



# 2018 Taiwan ESD and Reliability Conference

Dates: Nov. 7-9, 2018

Location: National Chiao Tung University, Hsinchu, Taiwan

Organizer: (1) Taiwan ESD Association; (2) Consortium of ESD Protection Technology for Circuits and Systems

Conference Website: <http://www.alab.ee.nctu.edu.tw/~esd/TESDC/>

Electrostatic Discharge (ESD) and reliability are critical issues for IC products with increased complexity in various processes. In order to improve the ESD and reliability related R&D capability, the 2018 Taiwan ESD and Reliability Conference is going to be held during Nov. 7-9, 2018, which is technically sponsored by Taiwan ESD Association (T-ESDA). Disclosures on ESD and reliability related experiences and research results are welcome, so that practical discussions and solutions can be obtained. Through the communications provided by this conference, the principles of the practical world experiences will be explained.

## ORGANIZING COMMITTEE

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### T-ESDA Secretariat

E-Mail: [service@t-esda.org](mailto:service@t-esda.org)

## Call for Papers

This conference focuses on the ESD protection and reliability related technologies. Papers related to the studies on analysis and solutions for practical cases are specifically interested.

Topics of interest include, but are not limited to:

### I. Component Level ESD Issue

• On-Chip Protection Techniques • EOS/ESD Failure Analysis • ESD Device and Circuit Simulation • Transmission Line Pulsing • RF Technologies and Compound Semiconductors • Processing Issues and Effects • IC Design and Layout Issues, including Packaging • Modeling and Physics of EOS/ESD • Advanced Fabrication Issues (FinFET, 3DIC, etc.)

### II. System-Level ESD/EMI Issue

• Simulators, Calibration and Correlation • Case Studies, Reviews and Analysis • Optical Networks ESD • EMI Filters • Test Methods and Procedures • Detection and Measurement Techniques • Modeling and Simulation.

### III. Factory-Level ESD Issue

• Packaging and Handling • Case Studies, Reviews and Analysis • Test Methods and Procedures • Transient ESD/EMI Induced Upset • Air Ionization and Uses • Troubleshooting Techniques • Facility Design • Management Issues (cost/benefit analyses, etc.)

### IV. ESD Materials Technology

• ESD Control Materials • ESD Shunting Packaging Technology • Use of Antistatic Materials • Test Methods and Procedures • Chemistry • Case Studies and Analysis.

### V. ESD Testing – Components, System, Factory & Materials

• Test Methods and Procedures • Round-Robin Testing, Results and Analysis • Standards - Comparisons and Analysis • Case Studies.

### VI. Reliability and Product Failure Analysis

• Test Structures for Reliability Assurance • Transistor, Thin Film and Interconnect Reliability • Electronic and Opto-electronic Package Reliability • Operation Environmental Impact on Electronic Reliability • Accelerated Life Tests • Burn-in and Screening • Failure Identification and Analysis • Reliability Lifetime Prediction.

### VII. Recent Patents on ESD and Reliability

• Review or Research Article on Important Patent Area in ESD or Reliability

## Information for Authors

1. Papers should be accomplished in A4 paper size with article length of 4-6 pages. It should be in a camera-ready format. The submission shall be made electronically (in PDF format).
2. **Paper Submission Deadline: Sep. 1, 2018**
3. Paper Acceptance Announcement: Oct. 1, 2018
4. About the paper format and the most updated news release, please visit URL <http://www.alab.ee.nctu.edu.tw/~esd/TESDC/>